

Booth No.

Invited by

# The Total Solution Exhibition for Electronic Equipment 2023

## INVITATION

5.31<sub>Wed.</sub> → 6.2<sub>Fri.</sub> 10:00-17:00

Tokyo Big Sight

East Exhibition Halls 2-6 & Conference Tower

It all starts here! ~ Exhibition X ~



No. 230531

Managed by: **JPCA** Japan Electronics Packaging and Circuits Association

Co-operated by: **WECC** / **CPCA** / **EIPC** / **ELCINA** / **HKPCR** / **IPC** / **IPCA** / **KPCA** / **THPCA** / **TPCA**

KPIA (Korea Packaging Integration Association) / AEIS (Association of Electronic Industries in Singapore)

\*Please enter above No. at the visitor registration.

### Overview

**JPCA 2023 Show**  
52nd International Electronic Circuits Exhibition

**JIEP** Microelectronics Show  
37th ADVANCED ELECTRONICS PACKAGING EXHIBITION

**JISSO PROTEC 2023**  
24th Jissou Process Technology Exhibition

**SDGs デバイス展**  
SDGs Device Show

**WIRE Japan Show**  
Connecting Devices to Devices  
Electrical / optical transmission technology

**Electronics Component & Unit Show**  
JEPF Japan Federation Of Electronic Parts Distributors And Dealers  
Tokyo Electronics Appliances Wholesalers Association

**E-Textile / Wearable**  
E-Textile / Wearable

**Smart Sensing**  
Smart Sensing

**無人化ソリューション展**  
Unmanned Solution Exhibition

**Edge Computing**  
Edge Computing

**INTEROPTO**  
INTERNATIONAL OPTOELECTRONICS EXHIBITION  
interOpto

**Imaging Japan**  
Imaging Japan

Date: May 31 (Wed.) – June 2 (Fri.), 2023

Open Hours: 10:00 – 17:00

Venue: Tokyo Big Sight East Exhibition Halls 2-6 & Conference Tower

Entrance Fee: 1,000 JPY (tax included) \*Free admission with online registration

### Visitor Information

Online Registration is required to visit the Total Solution Exhibition for Electronic Equipment. Please register via the official website in advance. It will not be possible to enter the exhibition with just this invitation.

#### STEP 1

Complete visitor registration via the official homepage

#### STEP 2

An email will be sent to your registered email address to set up your password. If you do not receive the password setup e-mail, please contact the Secretariat.

#### STEP 3

Print out the admission badge (visitor badge) from Visitor Portal and bring it with you in a four-folded format on the day you visit the exhibition.

### Official Website



Check the official website for the latest information

### Access & Venue Map

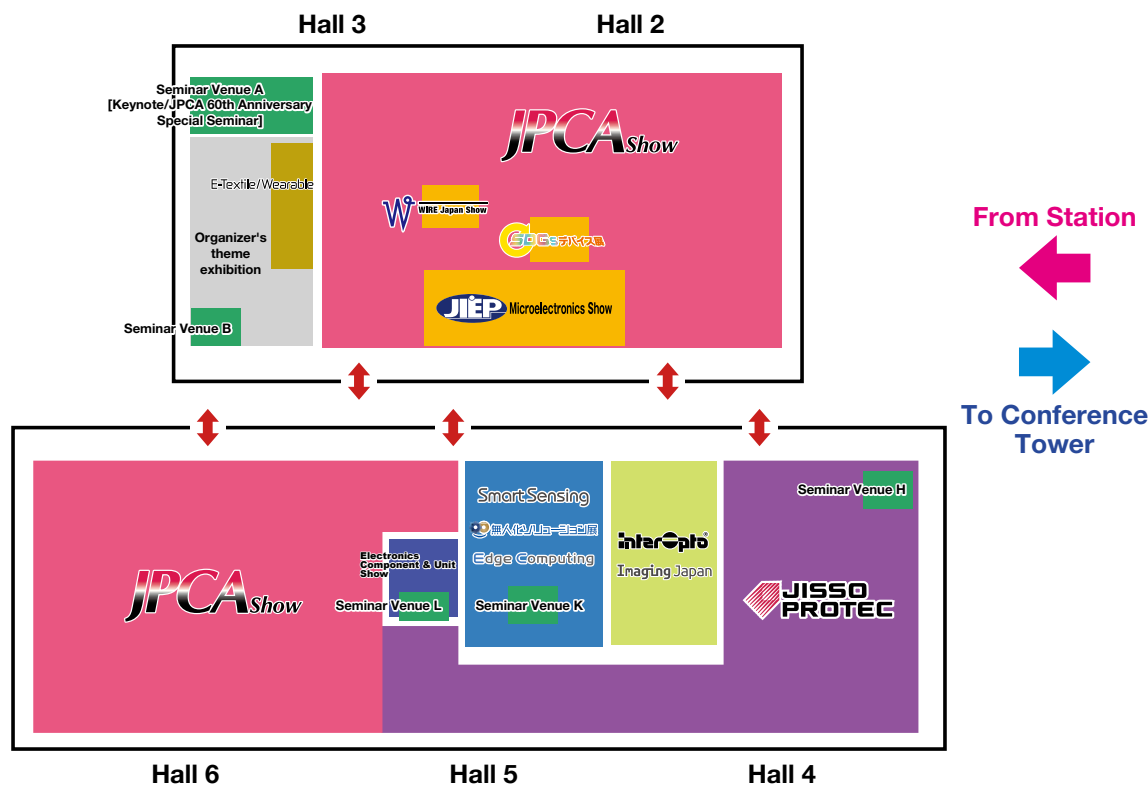


Access <https://www.bigsight.jp/english/visitor/access/>

Area Map [https://www.bigsight.jp/english/download/pdf/area\\_map\\_e.pdf](https://www.bigsight.jp/english/download/pdf/area_map_e.pdf)



## Layout in the Exhibition Hall



## List of Exhibitors

(As of April 14, 2023)

Sponsors			
Platinum			
ADTEC ENGINEERING			
MEIKO ELECTRONICS			
V Technology			
Gold			
Atotech Japan			
Dynatron			
Electro Scientific Industries Japan			
FICT			
MacDermid Performance Solutions Japan			
MEC			
TAIYO INK MFG			
Silver			
KYOSHA			
Showa Sangyo			
Bronze			
JPCA Plating Committee			
Kanai Juyo Kogyo			
NIKKAN INDUSTRIES			
TOA MUSENDEKI			
JPCA Show			
PWB Tech			
actnano			
ADTEC ENGINEERING			
AGFA Materials Japan			
AIN			
ALMEX TECHNOLOGIES			
atg Luther & Maelzer			
Atotech Japan			
AURONA INDUSTRIES			
Aztec			
AZUMA			
BEAC			
BRUX JAPAN			
CHEMITOX			
CHEMITRON			
CHEON WESTERN (CHINA) GROUP			
China Circuit Technology (Shantou)			
China Printed Circuit Association (CPCA)			
Daicel			
Daiwa			
DAIWA			
DE NORA PERMELEC			
Dempa Publications			
Denka			
Di-Nikko Engineering			
Dynatron			
EIGHTKOUGYOU			
Electro Scientific Industries Japan			
Electronic Circuit Pension Fund			
E-SONG EMC			
Everett/Charles Japan			
FICT			
FISCHER INSTRUMENTS			
Forewin Flex			
FSQuality			
Fuji Polymer Industries			
FUJIMORI KOGYO			
Fujiprix			
Fukuda Metal Foil & Powder			
FURNACE			
Goal Searchers, ZHUHAI			
GUANGDONG CHAMPION ASIA ELECTRONICS			
HAA OPTICS			
HAKUTO			
Hirox			
Hitachi High-Tech Science			
Hong Kong Printed Circuit Association (HKPCA)			
HWIN TRADING			
ICHIKAWA TECHNO FABRICS			
IDAJ			
Ihara Electronic Industries			
IMV			
INCOM			
inspec			
INTERXSOFT			
ISHIHARA CHEMICAL			
Ishii Hyoki			
ISUZU SEISAKUSHO			
IWAKI			
IZUMO CITY			
JABURO INDUSTRY			
JADASON Enterprises			
Japan Electronics and Information Technology Industries Association (JEITA)			
Japan Electronics Packaging and Circuits Association (JPCA)			
Japan Thermosetting Plastics Industry Association			
Japan Viewworks			
JCU			
Jiangsu Provision Electronics			
JIANGXI JIANGNAN NEW MATERIAL TECHNOLOGY			
J-RAS			
JTDM			
Kagoshima Prefectural			
Kanai Juyo Kogyo			
KANEKA			
KANEMATSU			
KFE Hong Kong			
KITAGAWA SEIKI			
KIYOKAWA Plating Industry			
Korea Packaging Integration Association (KPIA)			
Korea Printed Circuit Association (KPCA)			
Kumamoto Prefecture			
KURABO INDUSTRIES			
KYOEI PRINT GIKEN			
KYOSHA			
LPKF Laser & Electronics			
MacEight			
MACOHO			
MEC			
MEIKO ELECTRONICS			
Meltex			
MicroCraft			
MICROTECHNOLOGY			
MIKADO TECHNOS			
Minami Shiretoko Brown Bear Information Center			
MITSUBISHI ELECTRIC			
Mitsubishi Gas Chemical			
MORITANI			
MOTORONICS			
MURAKI			
NAKAJIMA KAGAKUSANGYO			
NIDEC ADVANCE TECHNOLOGY			
Nihon Micron			
NIKKAN INDUSTRIES			
Nikko-Materials			
Nikko Trans			
NIKON / NIKON SOLUTIONS			
NIPPO ELECTRONICS			
NISOUL			
NITTOBOSEKI			
NTW			
OFUNA ENTERPRISE JAPAN			
OKADA GAJ			
ONTEC			
ORC MANUFACTURING			
OTSUKA OPTICS			
PAN-TEC			
PCBGOGO			
PLAMEX			
Printed Circuit Journal			
PSIA (PUBLIC SECURITY INTELLIGENCE AGENCY)			
RAYON INDUSTRIAL			
Resonac			
RISHO KOGYO			
Ryoden			
SAGAMI PCI			
Sakigake Semiconductor			
SAN-EI KAGAKU			
SANKO GIKEN KOGYO			
Schmoll Maschinen			
SCREEN PE Solutions			
SHANDONG SHENGQUAN NEW MATERIALS			
SHENGYI TECHNOLOGY			
Shenzhen Jingxin Electronic Technology			
SHENZHEN JINZHOU PRECISION TECHNOLOGY			
Shenzhen Mason Electronics			
SHENZHEN NEWCESS INDUSTRIAL			
Shibecha-cho			
SHIBUYA			
SHIKOKU CHEMICALS			
SHIMANE FUJITSU			
Shinewell Technology (Hongkong)			
SHINKO			
Shinko Denki			
Shirai Electronics Industrial			
SHODA TECHTRON			
Showa Sangyo			
Stella			
Stella Corporation			
TAESUNG			
Taisei Laminator			
Taiwan Printed Circuit Association (TPCA)			
TAIYO INDUSTRIAL			
TAIYO INK MFG			
TAKANO			
TAKEUCHI			
TCT (JAPAN)			
TECHNOPRO MARUGEN			
TESPRO			
TESTONIC			
Tokyo Machine & Tool			
Tsukamoto Terada Laboratory Graduate School of Engineering Kobe University			
TSUNODA BRUSH			
Tulip			
UNION TOOL			
USHIO			
V Technology			
Via Mechanics			
WAZAM NEW MATERIALS			
World Electronic Circuits Council (WECC)			
Yamagata University YU-FIC			
YAMAHA FINE TECHNOLOGIES			
3D-MID Pavilion			
DAIEI ELECTRONICS			

Iwate Industrial Research Institute
Japan MID Association
TAIYO INK MFG.
Wonder Future Corporation
ZUKEN
Module Japan
ADEKA
AJ
AS ONE
Carl Zeiss
CITIZEN ELECTRONICS
EXSEAL
FORESIGHT
FUJIKIKO
JSR
NAGASE
NAITO DENSEI KOGYO
Nippon BARNES
NIPPON ELECTRIC GLASS
OKUNO CHEMICAL INDUSTRIES
Sanki Seisakusho
SEAKI PRECISION
SHIMIZU
TOWATEC
Flexible Printed Circuits Products Area
COMPLEX MICRO INTERCONNECTION
GIGAVIS
HAKKOH DENSHI
ISC
Korea Electronics Technology Institute
MEIWA CORPORATION
Ningbo Jujia New Material Technology
Oki Electric Cable
SHIIMA Electronics
Wonder Future Corporation
YAMASHITAMATERIALS
EMS Japan
FUJI ELECTRONICS
Luci
ODTECH
PRIMETECH ENGINEERING Yokohama
Factory
WAKOH DENKEN

Microelectronics Show
Addison Clear Wave Coating
EME
NIKKISO
The Japan Institute of Electronics Packaging (JIEP)
eX-tech
Advanced Materials Technology
AKITA CHMICAL INDUSTRIES
Andor System Support
ATENE
ePrint
ESPEC
Fujikura Kasei
HITACHI POWER SOLUTIONS
HONNY CHEMICALS
JNC Corporation
JNC Petrochemical
KUTSUZAWA
Melco Semiconductor Engineering
NIHON SUPERIOR
Nippo
Nordson
OSAKA ORGANIC CHEMICAL INDUSTRY
Plasma Ion Assist
PMT
SETOLAS Holdings
Shimada Appli
Shinryo
TA Instruments Japan
TEG SOLUTION
Toshiba Business Expert

Academic Plaza
Advanced Magnetic Devices (Sato & Sonehara) Lab., Dep. of Elect. and Computer Eng., Fac. of Eng., Shinshu Univ.
Canal Water
CITIZEN FINEDEVICE
Department of Mechanical and Electrical Engineering, Suwa University of Science
Ehime University
EXTCOM
Graduate School of Engineering Kanto Gakuin University

Graduate School of Science and Technology, Gunma University
GreenChem
Hidekazu Tsuchiya Lab., Tokai Univ.
Hokkaido University, Faculty of Engineering, Yonezawa Lab.
IWATE UNIVERSITY
Japan Kanigen
Kyushu Univ.
Local Independent Administrative Agency Kanagawa Institute of industrial Science and Technology
Nakayama Lab., National Institute of Technology (KOSEN), Nagano College
Nihon University
Oki Engineering
Organization for Regional Collaborative Research and Development, Suwa University of Science
Osaka Metropolitan University
PALMENS
Phototechnica
Research Institute for Electromagnetic Materials
Rikimaru Lab., National Institute of Technology (KOSEN), Nagano College
Sanyo-Onoda City University
Spin Device Technology Center
Tohoku University
Tokushima University
Tokyo Polytechnic University
Tokyo University of Science
Yamagata Research Institute of Technology
Yokohama National University

JISSO PROTEC
ALPHA ELECTRONICS
AYUMI INDUSTRY
BozhonJapan
Brooks Japan
CKD
EIGHTECH TECTRON
FANUC
FUJI
Gicho business communications
HAKKO
HELLER INDUSTRIES
HIWIN
ICHINEN MANUFACTURING
Japan Robot Association (JARA)
JFE Shoji Electronics
JUKI
JUTZE JAPAN
KAKEN TECH
Kawasaki Heavy Industries
Lux
MALCOM
MIRTEC JAPAN
MUSASHI ENGINEERING
NIHON SUPERIOR
Nippon Thompson
OKUDA TRADING
Okuhara Electric
OMRON
Panasonic Connect
PARMI JAPAN
PASSCON
PEMTRON
PROCESS LAB. MICRON
SAYAKA
Shoritsu Electric Industry
TAIYO ELECTRIC IND.
TAMURA CORPORATION
Techno Alpha
Toyo Living
Wing Vision
YAMAHA MOTOR


SDGs Device Show
ASOPICS
Sangyo-times

WIRE Japan Show
KOGYO TSUSHIN
TATSUTA Electric Wire and Cable

Electronics Component & Unit Show
CoreStaff

DAIWAMUSENDENKI
GLOBAL DISPLAY
HIKAWA ELECTRONICS
IIDA ELECTRONICS (TSUSHO)
JAPAN FEDERATION OF ELCTRONIC PARTS DISTRIBUTORS AND DEALERS (JEP)
METRO ELECTRIC
Nagoya Rikendengu
NNP
Okamoto Electronics
R-DENSHI
Sankyosha
Seidensha
SETTSU METAL INDUSTRIAL
TOA MUSENDENKI
Tokyo Electronics Appliances Wholesalers Association (TEP)
TOMINAGA ELECTRIC
TORII
Tsuruta Seigyo Kiki

E-Textile/Wearable
AITOZ
DAIKI
Japan Media Systems
JOHNNAN
SENKEN SHIMBUN
Smart Textile Collaborative Research Promotion Committee of Ishikawa
SUNCORONA ODA
The University of Tokyo
URASE
Xacti
Yonezawa Bussan

Smart Sensing  無人化ソリューション展
ALPSALPINE
Asahi Rubber
Astron
Atmark Techno
Ball Wave
CONNECTEC JAPAN
Cornes Technologies
DELTA TOOLING
Digi International
DynaCmware
e.x.press.
Energy Harvesting Consortium
FUJITOKU
FUJITSU COMPONENT
Fukuda Crystal Laboratory
Gazo
Global Information
HortPlan
IDTechEx
Innovation Research
IR System
Izuma Networks
Japan Display
Kanazawa University V-COLLABO
Kanazawa University Vibrational Power Generator Laboratory
KLV
Kobe Digital Labo
KODENSHI
KRONE
Maxell
Micro Module Technology
Mio Corporation
MODE
monodukuri.com
MULTISOUP
NAITO DENSEI MACHIDA MFG.
NANOXEED
Narcohm
National Institute of Advanced Industrial Science and Technology (AIST)
NGK INSULATORS
NICHIDEN
NTT Advanced Technology
Polytec Japan
Robotic Increase Center
RTC
SENSIRION JAPAN

SMK
SOFTAGENCY
SUMITOMO METAL MINING PLANNING & ADMINISTRATION DEPT. TECHNOLOGY DIV.
Teikoku Printing Inks Mfg
Tohoku University Frontier Research Institute for Interdisciplinary Sciences Shimatsu Laboratory
TokaiRika
Tokyo Ohka Kogyo
Touchence
TSUBAKIMOTO KOGYO
Tycoh
YASHIMA ELECTRIC
YITOA Micro Technology
Yokoyama Shokai

INTERNATIONAL OPTOELECTRONICS EXHIBITION 
ADVANCED COMMUNICATION MEDIA
ADVANTEST
AIM
AIO Core
Alnair Labs
Chitose Institute of Science and Technology
City of Chitose
DAICO MFG
DongGuan WuFeng Electronics
E&E Evolution
Genial Light
Graviton
HORIBA
Institute of Post-LED Photonics, Tokushima University
IR System
J.A.WOOLLAM JAPAN
JAPAN IMPOTERS ASSOCIATION OF LASERS & ELECTRO-OPTICS
KOHOKU KOGYO
Kyoto Photonics Society
Laser Focus World Japan
MARUBUN
MICROSIGNAL
MICTEC
Nagaoka University of Technology
National Institute of Technology, Anan College
Nitto Optical
Optoelectronics Industry and Technology Development Association (OITDA)
OPTRONICS
ORANGEARCH
Photonic Edge
Photonic Science Technology
Photonics Electronics Technology Research Association (PETRA)
PHOTOTECHNICA
Pi PHOTONICS
Research Foundation for Opto-Science and Technology
RIKEN
Shibahara Manufacturing Industry
SHIMADZU
Space Photon
Spectra Design
Stella
SteraVision
SUMITOMO ELECTRIC INDUSTRIES
SYNERGY OPTOSYSTEMS
TECHNOHANDS
Terahertz Technology Forum
The Graduated School for the Creation of New Photonics Industries
The international society for optics and photonics (SPIE)
The Japan Society of Laser Technology
The Korea Association for Photonics Industry Development (KAPID)
Tokai Engineering Service
UBE
ZHEJIANG LANTE OPTICS
Zhongshan Sichuang Optoelectronics Technology

Imaging Japan
Caeleste CVBA
Cybernet Systems
EBA JAPAN
Micron
Mitsunami
Nissin Kikai
Taihei Boeki
VS Technology





		Seminar Venue G	Seminar Venue M
May 31	10:55-11:15	<b>Hotmelt dispenser: the ultimate solution for bonding, sealing and lubricating of small electronic/wearable device.</b> Nordson K.K.	<b>Liquid crystal polymer (LCP) materials and its application to textiles and electronic components</b> Ningbo Jujia New Material Technology Co., Ltd.
	11:35-11:55	<b>Introducing new surface modification technology!</b> (Improvement of droplet accuracy by liquid-repellent treatment that does not require coating agents, reduction treatment that does not require gas) Sakigake Semiconductor	<b>Introduction of our New and Unique FPC.</b> Oki Electric Cable Co.,Ltd.
	12:15-12:35		<b>Simultaneous monitoring of all measuring instruments! With 26 years of experience in software development, we challenge new added value of IoT technology.</b> SOFTAGENCY CO., LTD.
	13:35-13:55		<b>The Coming Together of Edge Computing and the Cloud</b> Izuma Networks
	14:15-14:35		<b>Introduction of BT resin laminates with high dielectric constant</b> MITSUBISHI GAS CHEMICAL CO., INC.
	14:55-15:15		<b>Multi-Step Stencil enabling simultaneous mounting of large and small components with flexible layout</b> BRUX JAPAN CO., LTD.
June 1	10:55-11:15	<b>Ushio's Lihography tool and Excimer.</b> USHIO INC.	<b>New manufacturing "MONODUKURI" realized by IH reflow</b> <b>Supports mass production of electronics parts mounting on low-heat and high-heat-dissipation substrates</b> Wonder Future Corporation
	11:35-11:55	<b>Introduction of laser processing machines for substrate and electronic component processing</b> SHIBUYA CORPORATION	<b>FPC + Wire harness</b> COMPLEX MICRO INTERCONNECTION CO.,LTD
	12:15-12:35		<b>Introduction of insulation performance evaluation technology for power device materials and how to use UL Data Acceptance program and ASP evaluation</b> CHEMITOX, Inc.
	12:55-13:15	<b>Data direct solutions</b> Dynatron Co.,LTD.	
	13:35-13:55	<b>New film coating system (This is the world's first invention system)</b> Shimada Appli G.K.	<b>Introduction of BT resin laminates for FC-BGA package</b> MITSUBISHI GAS CHEMICAL CO., INC.
	14:15-14:35	<b>Printed Circuit Board Exposure Technologies</b> V Technology Co., Ltd.	<b>Ultra-compact matchbox-sized laser.</b> <b>Introduce the state of art trends and application examples of the MatchBox series.</b> PHOTOTECHNICA CORPORATION
	14:55-15:15	<b>Introduction of JTAG Boundary scan test that solves the problems of BGA package device mounted board inspection</b> ANDOR SYSTEM SUPPORT CO., LTD.	<b>New products of Abrasive Wheel for printed circuit board manufacturing process</b> <b>Abrasive wheel that correspond to clogging before forming solder resist</b> <b>Abrasive wheel for removing plugging ink</b> Kanai Juyo Kogyo Co.,Ltd
	15:35-15:55	<b>Introduction of inkjet coating technology</b> ISHII HYOKI Co., LTD	<b>How to completely remove sub-micron contamination without damaging on PCB</b> BRUX JAPAN CO., LTD.
	16:15-16:35		<b>Creation of DX and new digital marketing</b> TOAMUSEN DENKI CO.,LTD
June 2	10:15-10:35	<b>Development of Sintering Equipment for Power Semiconductors Applying 3D Press Technology</b> NIKKISO CO., LTD.	<b>Redefining the Economics of Laser Depaneling</b> <b>New era of LPKF laser depaneling technology</b> LPKF Laser & Electronics K.K.
	10:55-11:15		<b>The Latest Technology of FANUC Robots</b> FANUC CORPORATION
	11:35-11:55	<b>Visualize the characteristics of materials! Thermal analysis and viscoelasticity measurements of electronics materials.</b> TA Instruments Japan	<b>Introduction of acid copper plating process for fine line patterning formation.</b> Meltex Inc.
	12:15-12:35		<b>Latest technical information for PCB tools.</b> UNION TOOL .CO
	12:55-13:15	<b>Adoption example of DLC in the manufacturing process of electronic components and semiconductors.</b> <b>Introduction of various functional DLC such as low-dielectric DLC for the 5G communication band.</b> Plasma Ion Assist Co.,Ltd.	<b>HORIBA's optical components (gratings, detector, spectrometer and IR modules) and examples of customizing them for each customers.</b> HORIBA, Ltd.
	13:35-13:55	<b>Introduction of various low-temperature curing adhesive materials and solder pastes that are compatible with carbon-neutral and low-stress bonding</b> Nippo LTD.	<b>Okuno's solutions by copper electroplating additives for semiconductor package substrates (For large diameter vias, for high-speed transmission, for ultra-fine FOWLP and FOPLP)</b> OKUNO Chemical Industries Co., Ltd.
	14:15-14:35	<b>Introduction of PCB design AI automatic placement solution</b> ONTEC.CO.,LTD	<b>Using LTspice for PCB design.</b> <b>(Focusing on the trace of the SW power supply section and the inductance component of the VIA.)</b> Sankyo Co.,Ltd.
	14:55-15:15	<b>Introduction of new product Maglev Pump MJ-100</b> IWAKI CO., LTD.	
	15:35-16:35		<b>Recycling of copper and water is realized by improving wastewater treatment technology in the plating factory.</b> PLAMEX CO., LTD.



## The Total Solution Exhibition for Electronic Equipment Keynote (JPCA 60th Anniversary)










Admission Fee Required

Free for VIP/Members




Pre-Registration Required

Seminar Venue A




[Admission Fee] Members: Free Non-Members: 20,000JPY / 1 session \*tax included \*JPCA Members, JIEP Regular / Supporting / Student Members, JARA Regular / Corporate Supporting Members, JEP・TEP Members

May 31		June 1	June 2
SDGs Electronic Devices		Mobility	Future of Semiconductor
10:45 ~ 11:30	 <b>Aiming for high growth with the Metaverse and SDGs!</b> -Focus on large-scale semiconductor projects in Japan and around the world- Mr. Wataru Izumiya Sangyo-times, Inc	 <b>Freedom of Mobility for All</b> -Toyota's Automated Driving Technology Development- Mr. Ken Koibuchi Toyota Motor Corporation	 <b>Industry of Semiconductor and Semiconductor Process Equipment</b> <b>Its Future and Challenges</b> Prof. Akinobu Teramoto Hiroshima University, Research Institute for Nanodevices Director & Professor
Semiconductor / Package		Robot / Automation	Japan's Semiconductor Strategy
11:45 ~ 12:30	 <b>Current Status and Future Direction of Semiconductor and Digital Industry Strategy</b> Mr. Yohei Ogino Ministry of Economy, Trade and Industry. Commerce and Information Policy Bureau, Device Industry and Semiconductor Strategy Office, Director	 <b>Labor shortages that will challenge the manufacturing industry and automation proposals for the electronics industry</b> ~ In pursuit of automation that can easily be introduced to manufacturing sites ~ Mr. Kenji Yamaguchi FANUC CORPORATION, Representative Director President and CEO	 <b>Japan's semiconductor Strategy</b> ~ More Moore, More than Moore, More People ~ Prof. Tadahi Kuroda The University of Tokyo
SiC Power Semiconductor		Unmanned / IoT	Wearable / E-Textile
13:30 ~ 14:15	 <b>Power devices and Analog Technology becoming increasingly important for a decarbonized society</b> Mr. Isao Matsumoto ROHM CO., Ltd. President, Chief Executive Officer	 <b>Power of Change &amp; Connection for IoT Assembly Revolution</b> Mr. Katsunori Hirata Representative Director, President CONNECTEC JAPAN Corporation	 <b>Wearable Devices Open Up a New Relationship between Humans and Computers: Medicine, Healthcare, Education, and Entertainment</b> Prof. Tsutomu Terada Kobe University, Graduate School of Engineering Professor

# JPCA 60th Anniversary Special Seminar Free Pre-Registration Required Seminar Venue A

	May 31	June 1	June 2
	<b>History and Prospects of Electronics</b>	<b>Flying Car</b>	<b>Semiconductor / Packaging Technology</b>
14:30 15:30	 <b>Innovation Wave on the Electronics industry</b> <b>Mr. Mikio Katayama</b> The University of Tokyo, Institute of Industrial Science, Research Advisor Kconcept Co.,Ltd, CEO (Former President of Sharp)	 <b>New business chance for Air mobility market</b> <b>Mr. Hisashi Asai</b> AirMobility Inc., President & CEO	 <b>Dawn of a new era for the global semiconductor innovation</b> <b>Dr. Atsuyoshi Koike</b> Rapidus Corporation, President & CEO

# JISSO PROTEC Special Seminar Free Pre-Registration Required Seminar Venue H

	May 31	June 1	June 2
10:30 11:20	 <b>Smartphone/peripherals sector outlook</b> <b>Mr. Yasuo Nakane</b> Mizuho Securities Co., Ltd. Equity Research Dept. Global Head of Technology Research Senior Analyst	 <b>JEITA Japan Jisso Technology Roadmap 2022 "Focused Markets and Electronics"</b> - New markets to accelerate post-coronavirus and decarbonization - *JEITA: Japan Electronics and Information Technology Industries Association <b>Mr. Takashi Nishimura</b> Japan Electronics and Information Technology Industries Association, JJTRC, Chairman / Mitsubishi Electric Corporation, Advanced Technology R&D Center, Power Module Technology Department, Head Researcher	 <b>Bonding materials and electronics packaging technologies for the EV era</b> <b>Mr. Arihiro Kamiya</b> DENSO CORPORATION Semiconductor Basis Technology R&D Div.

# Electronics Component & Unit Show Seminar Free Pre-Registration Required Seminar Venue L

	May 1	June 1	June 2
15:45 16:30	<b>Introduction of an industry-government-academia collaborative development case for AR glasses utilizing eyeglass frame technology</b> <b>Mr. Masaaki Ashihara</b> Industrial Technology Center of Fukui Prefecture, Mechanical Engineering and Metallurgy Department Digital Technology Research Group Senior researcher	<b>Compact Full-color Laser Beam Projector Based on Waveguide-type Combiners</b> <b>Mr. Akira Nakao</b> University of Fukui Headquarters for Innovative Society-Academia Corporation Assistant Professor for Innovative Optoelectronics Device project	<b>Expanding the use of electronics ~ Application to the field of sports ~</b> <b>Mr. Junji Tsukamoto</b> CBC Co., Ltd. New Business Department Sports Business Unit Project leader

# Smart Sensing / Unmanned Solution Exhibition Innovation Summit Edge Computing Seminar Free Pre-Registration Required Seminar Venue K

## Keynote Speech

	May 31
14:40-15:30	<b>Global trend report and how to build service.</b> <b>Mr. Satoshi Ueno</b> MODE, Inc. VP of Business
	June 1
10:15-11:05	<b>Smart sensing towards Interverse Services</b> <b>Dr. Masaaki Mochimaru</b> The National Institute of Advanced Industrial Science and Technology, Human Augmentation Research Center, Director
11:35-12:25	<b>Product Development and Future Prospects of Magnetostrictive Vibration Power Generation Moving towards Social Implementation</b>
	June 2
11:35-12:00	<b>Improving operational efficiency by automating on-site logistics</b> <b>Mr. Kenji Mimura</b> MACNICA, Inc.
12:00-12:25	<b>Demonstrate with a live demo! Looking ahead to unmanned movement of people and goods - our Efforts to utilize mobility data -</b> <b>Mr. Taku Uehara</b> MACNICA, Inc.

## Special Session

	June 1
15:45-16:30	<b>Animal DX</b> <b>Mr. Yasushi Fujimoto</b> Minami Shiretoko Brown Bear Information Center, Chairman

# OITDA Seminar in 2023 [Photonics and Laser for Micro Fabrication and Industrial Future] Admission Fee Required Free for Members Pre-Registration Required Conference Tower, 1F, Room 102

	May 31
10:30-11:10	<b>Laser Micro Processing in "TACMI" Consortium</b> <b>Yohei Kobayashi</b> The University of Tokyo
11:10-11:50	<b>Present and Future of Laser Drilling for Printed Circuit Board</b> <b>Atsuhiko Kaneda</b> MITSUBISHI ELECTRIC Corporation
11:50-12:30	<b>Smart Glass Application and Future Development</b> <b>Masayuki Takagi</b> Seiko Epson Corporation
12:30-14:00	<b>Lunch break</b>
14:00-14:40	<b>Exploring the potential of micro and nano photonics European ecosystem</b> <b>Carlos Lee</b> EPIC
14:40-15:20	<b>Global Trends in Imaging and Sensing in AR/VR and Automotive Industries</b> <b>Jose Pozo</b> OPTICA

# E-Textile / Wearable Seminar Free Pre-Registration Not Required Seminar Venue B

	May 31
14:00-16:00	<b>Waigaya Round Table Progress Report Seminar for E-Textile Application Development</b> <b>Dr. Naoki Saiwaki</b> Nara National Institute of Higher Education and Research/Osaka University, Center for NARA Colleges Collaboration/Graduate School of Engineering Science, Professor - Director/Specially Appointed Professor

\*Please understand that the program is subject to change without notice. Please arrive at the registration desk early on the day of the seminar.